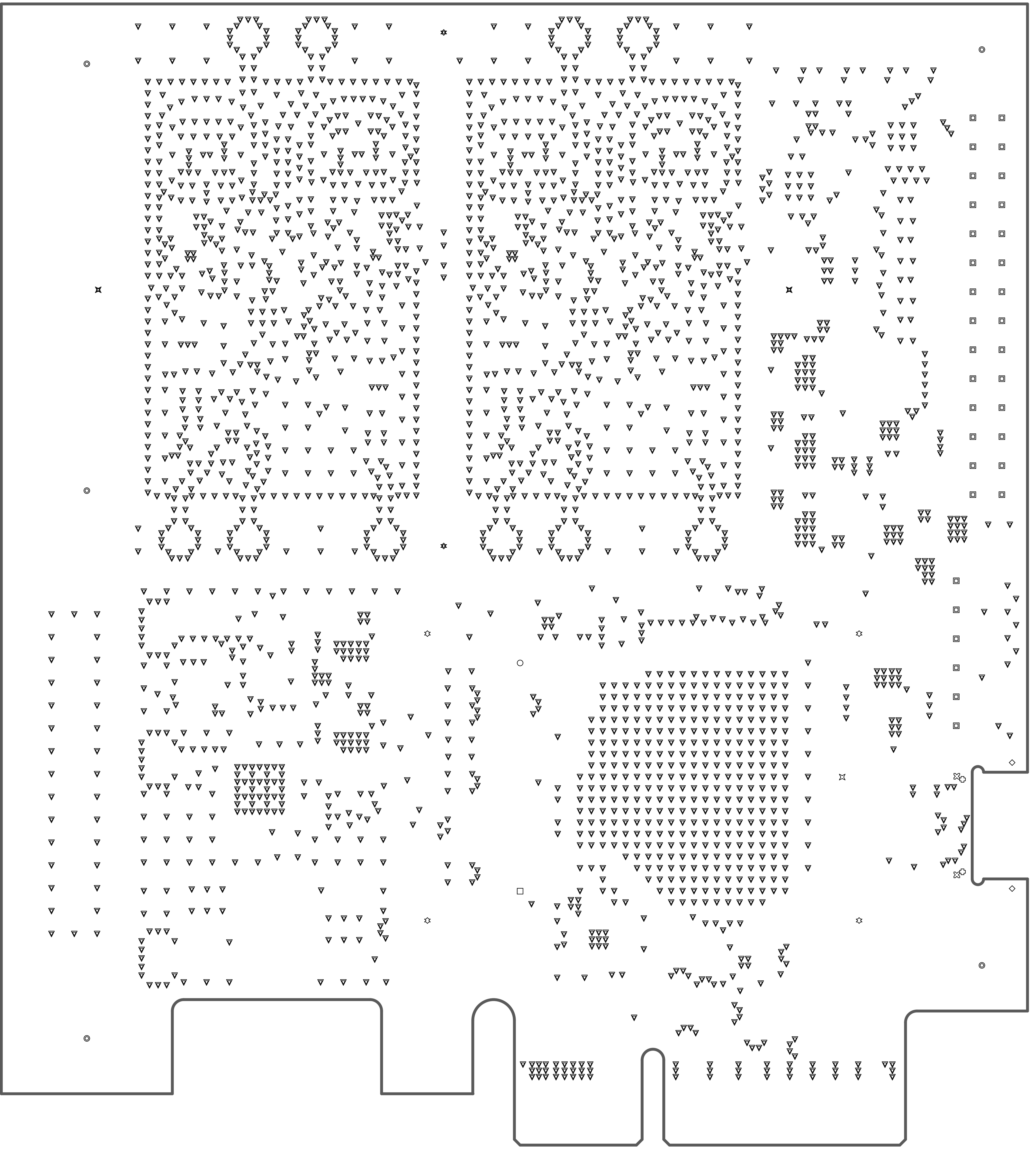
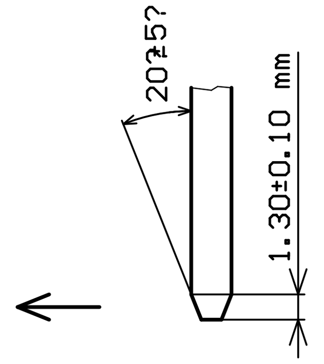


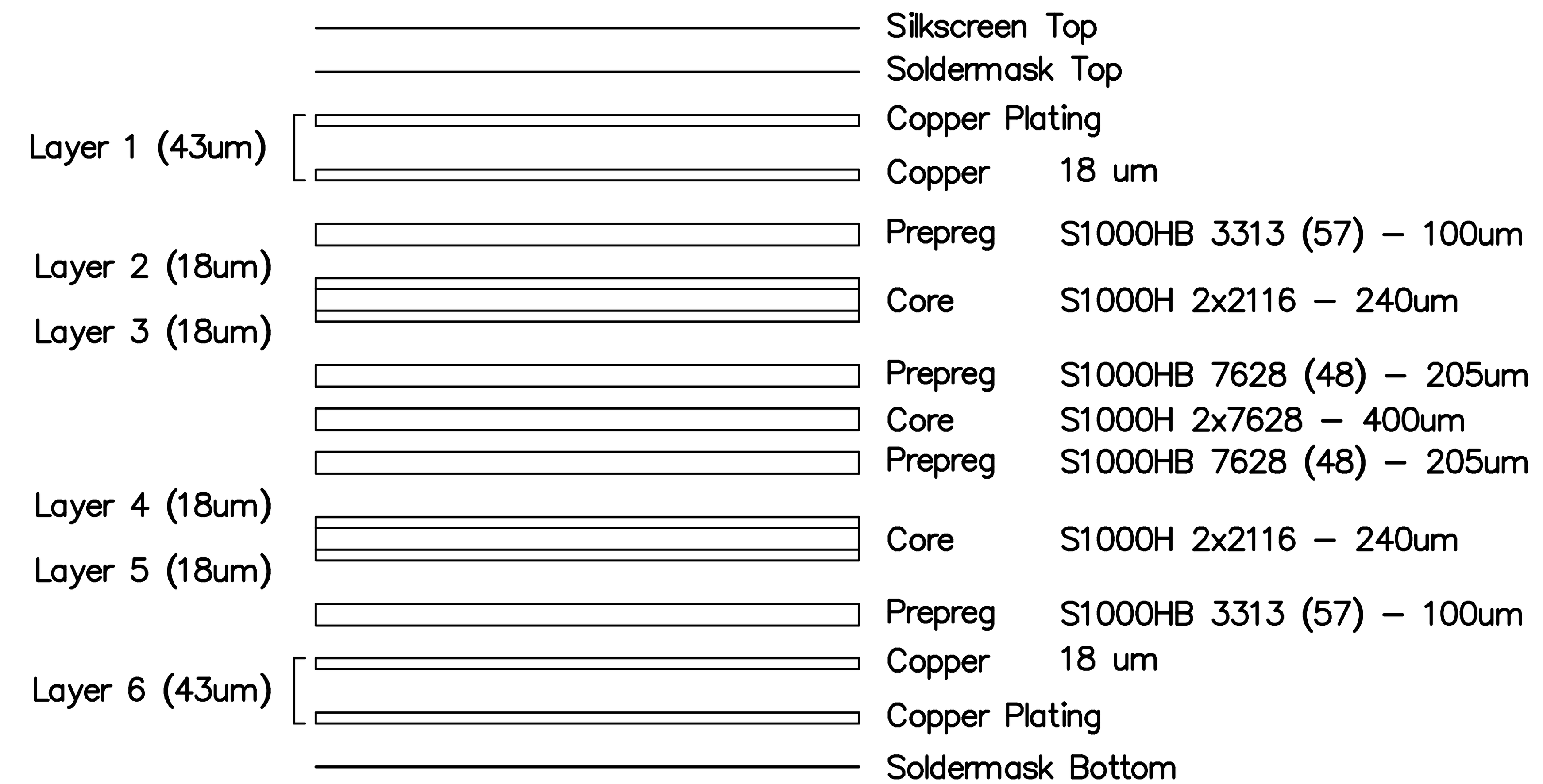


1. Used material – S1000H
2. Number of layers – 6
3. Board thickness – 1.6mm +/–10%
4. Thickness of outer layer (Cu) – 43um include copper plating
5. Thickness of inner layers (Cu) – 18um
6. Solder Mask – Two sides, Blue
7. Silkscreen – Yes, one side.
8. Type of coating – ENIG
9. Edge Connector – Hard Gold Au 0,2–0,5um/Ni 5um
10. Electrical Test on both side (use PCIe_to_M2_E.ipc file)
11. Min dia of plated hole – 0.2mm
12. Min trace width/clearance – 0.1mm/0.1mm
13. Impedance control – Yes, see details
14. Impedance tolerance – 10%
15. Board dimensions – 100mm x 90mm

Symbol	Hole Size	Hole Type	Plated	Count
∇	0.200mm (7.87mil)	Round	PTH	2680
◇	0.600mm (23.62mil)	Slot	PTH	2
✚	0.600mm (23.62mil)	Slot	PTH	2
⌧	0.600mm (23.62mil)	Slot	PTH	2
□	1.100mm (43.31mil)	Round	NPTH	1
▣	1.200mm (47.24mil)	Round	PTH	34
○	1.600mm (62.99mil)	Round	NPTH	1
✦	2.500mm (98.43mil)	Round	NPTH	2
✡	2.500mm (98.43mil)	Round	PTH	2
✧	2.600mm (102.36mil)	Round	PTH	1
✡	3.200mm (125.98mil)	Round	NPTH	4
◎	3.500mm (137.79mil)	Round	NPTH	5
				2736 Total

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Stack–Up



Impedance Requirement Table

Type	Layer	Ref. Layer		Trace Width	Trace Separation	Ground Spacing	Impedance
		Upper	Lower				
Single	1	–	2	0.150	–	0.200	50 Ohm
Single	5	6	4	0.100	–	0.200	50 Ohm
Differential	6	–	5	0.140	0.200	–	90 Ohm
Differential	1	–	2	0.120	0.250	–	100 Ohm
Differential	6	–	5	0.120	0.250	–	100 Ohm
Differential	5	6	4	0.100	0.270	–	100 Ohm